

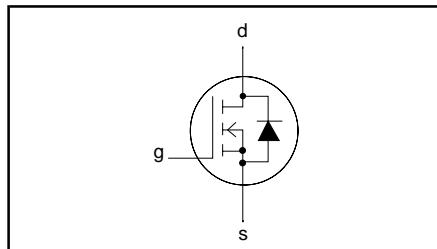
## N-channel TrenchMOS™ transistor Logic level FET

**PHP87N03LT, PHB87N03LT  
PHD87N03LT**

### FEATURES

- 'Trench' technology
- Very low on-state resistance
- Fast switching
- Low thermal resistance
- Logic level compatible

### SYMBOL



### QUICK REFERENCE DATA

$V_{DSS} = 25 \text{ V}$
$I_D = 75 \text{ A}$
$R_{DS(ON)} \leq 9.5 \text{ m}\Omega (V_{GS} = 10 \text{ V})$
$R_{DS(ON)} \leq 10.5 \text{ m}\Omega (V_{GS} = 5 \text{ V})$

### GENERAL DESCRIPTION

N-channel enhancement mode logic level field-effect power transistor in a plastic envelope using 'trench' technology.

#### Applications:-

- High frequency computer motherboard d.c. to d.c. converters
- High current switching

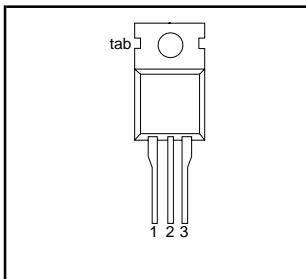
The PHP87N03LT is supplied in the SOT78 (TO220AB) conventional leaded package.

The PHB87N03LT is supplied in the SOT404 (D<sup>2</sup>PAK) surface mounting package.

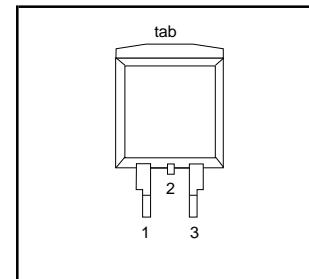
The PHD87N03LT is supplied in the SOT428 (DPAK) surface mounting package.

### PINNING

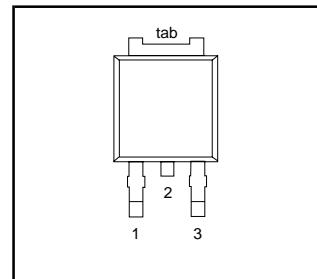
### SOT78 (TO220AB)



### SOT404 (D<sup>2</sup>PAK)



### SOT428 (DPAK)



### LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{DSS}$	Drain-source voltage	$T_j = 25 \text{ }^\circ\text{C to } 175 \text{ }^\circ\text{C}$	-	25	V
$V_{DGR}$	Drain-gate voltage	$T_j = 25 \text{ }^\circ\text{C to } 175 \text{ }^\circ\text{C}; R_{GS} = 20 \text{ k}\Omega$	-	25	V
$V_{GS}$	Gate-source voltage (DC)	$T_j = 25 \text{ }^\circ\text{C to } 175 \text{ }^\circ\text{C}; R_{GS} = 20 \text{ k}\Omega$	-	$\pm 15$	V
$V_{GSM}$	Gate-source voltage (pulse peak value)	$T_j \leq 150 \text{ }^\circ\text{C}$	-	$\pm 20$	V
$I_D$	Drain current (DC)	$T_{mb} = 25 \text{ }^\circ\text{C}$	-	75	A
		$T_{mb} = 100 \text{ }^\circ\text{C}$	-	61	A
		$T_{mb} = 25 \text{ }^\circ\text{C}$	-	240	A
$I_{DM}$	Drain current (pulse peak value)	$T_{mb} = 25 \text{ }^\circ\text{C}$	-	240	A
$P_{tot}$	Total power dissipation	$T_{mb} = 25 \text{ }^\circ\text{C}$	-	142	W
$T_j, T_{stg}$	Operating junction and storage temperature	$T_{mb} = 25 \text{ }^\circ\text{C}$	-55	175	$^\circ\text{C}$

<sup>1</sup> It is not possible to make connection to pin:2 of the SOT404 or SOT428 packages.

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### THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j\text{-}mb}$	Thermal resistance junction to mounting base		-	-	1.05	K/W
$R_{th\ j\text{-}a}$	Thermal resistance junction to ambient	SOT78 package, in free air SOT404 or SOT428 package, pcb mounted, minimum footprint	- -	60 50	- -	K/W K/W

### AVALANCHE LIMITING VALUE

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$W_{DSS}$	Drain-source non-repetitive unclamped inductive turn-off energy	$I_D = 45\text{ A}; V_{DD} \leq 15\text{ V}; V_{GS} = 5\text{ V}; R_{GS} = 50\text{ }\Omega; T_{mb} = 25\text{ }^\circ\text{C}$	-	200	mJ

### ELECTRICAL CHARACTERISTICS

$T_j = 25^\circ\text{C}$  unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}; I_D = 0.25\text{ mA}$	25	-	-	V
$V_{GS(TO)}$	Gate threshold voltage	$V_{DS} = V_{GS}; I_D = 1\text{ mA}$ $T_j = -55^\circ\text{C}$	22 1	- 1.5	- 2	V
$R_{DS(ON)}$	Drain-source on-state resistance	$V_{GS} = 5\text{ V}; I_D = 25\text{ A}$ $V_{GS} = 10\text{ V}; I_D = 25\text{ A}$ $V_{GS} = 5\text{ V}; I_D = 25\text{ A}; T_j = 175^\circ\text{C}$	0.5	-	-	V
$g_{fs}$ $I_{GSS}$ $I_{DSS}$	Forward transconductance Gate source leakage current Zero gate voltage drain current	$V_{DS} = 25\text{ V}; I_D = 25\text{ A}$ $V_{GS} = \pm 5\text{ V}; V_{DS} = 0\text{ V}$ $V_{DS} = 25\text{ V}; V_{GS} = 0\text{ V}; T_j = 175^\circ\text{C}$	- - - - - -	9 8.5 - 12 10 0.05	10.5 9.5 - - 100 10	$\text{m}\Omega$ $\text{nA}$ $\mu\text{A}$
$Q_{g(\text{tot})}$ $Q_{gs}$ $Q_{gd}$	Total gate charge Gate-source charge Gate-drain (Miller) charge	$I_D = 75\text{ A}; V_{DD} = 15\text{ V}; V_{GS} = 5\text{ V}$	- - -	39 9 18.5	- - -	nC nC nC
$t_{d\ on}$ $t_r$ $t_{d\ off}$ $t_f$	Turn-on delay time Turn-on rise time Turn-off delay time Turn-off fall time	$V_{DD} = 15\text{ V}; I_D = 25\text{ A}$ $V_{GS} = 10\text{ V}; R_G = 5\Omega$ Resistive load	- - - -	9 54 136 85	15 70 160 100	ns ns ns ns
$L_d$ $L_d$ $L_s$	Internal drain inductance Internal drain inductance Internal source inductance	Measured tab to centre of die Measured from drain lead to centre of die (SOT78 package only) Measured from source lead to source bond pad	- - -	3.5 4.5 7.5	- - -	nH nH nH
$C_{iss}$ $C_{oss}$ $C_{rss}$	Input capacitance Output capacitance Feedback capacitance	$V_{GS} = 0\text{ V}; V_{DS} = 20\text{ V}; f = 1\text{ MHz}$	- - -	2304 620 448	- - -	pF pF pF

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**REVERSE DIODE LIMITING VALUES AND CHARACTERISTICS**

$T_j = 25^\circ\text{C}$  unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_S$	Continuous source current (body diode)		-	-	75	A
$I_{SM}$	Pulsed source current (body diode)		-	-	240	A
$V_{SD}$	Diode forward voltage	$I_F = 25 \text{ A}; V_{GS} = 0 \text{ V}$ $I_F = 40 \text{ A}; V_{GS} = 0 \text{ V}$	-	0.85 0.9	1.2	V
$t_{rr}$ $Q_{rr}$	Reverse recovery time Reverse recovery charge	$I_F = 20 \text{ A}; -dI_F/dt = 100 \text{ A}/\mu\text{s};$ $V_{GS} = 0 \text{ V}; V_R = 25 \text{ V}$	-	109 0.2	-	ns $\mu\text{C}$

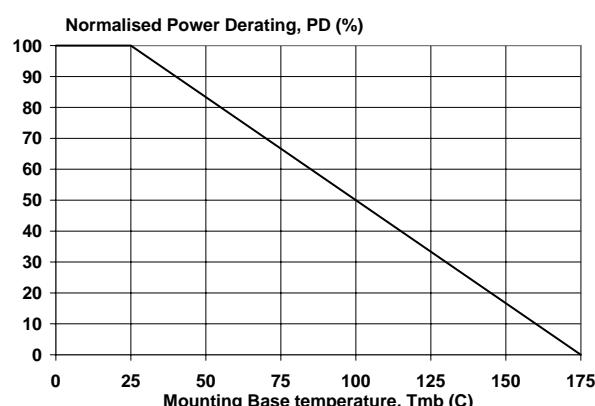


Fig. 1. Normalised power dissipation.  
 $PD\% = 100 \cdot P_D / P_{D, 25^\circ\text{C}} = f(T_{mb})$

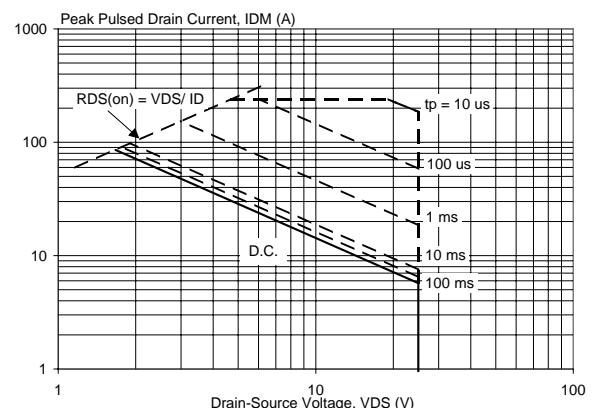


Fig. 3. Safe operating area  
 $I_D$  &  $I_{DM} = f(V_{DS})$ ;  $I_{DM}$  single pulse; parameter  $t_p$

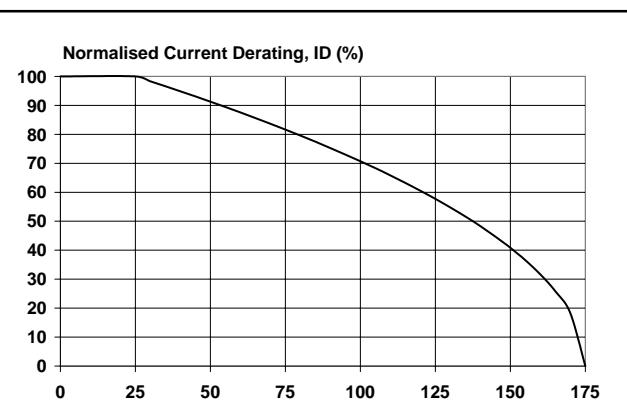


Fig. 2. Normalised continuous drain current.  
 $ID\% = 100 \cdot I_D / I_{D, 25^\circ\text{C}} = f(T_{mb}); V_{GS} \geq 5 \text{ V}$

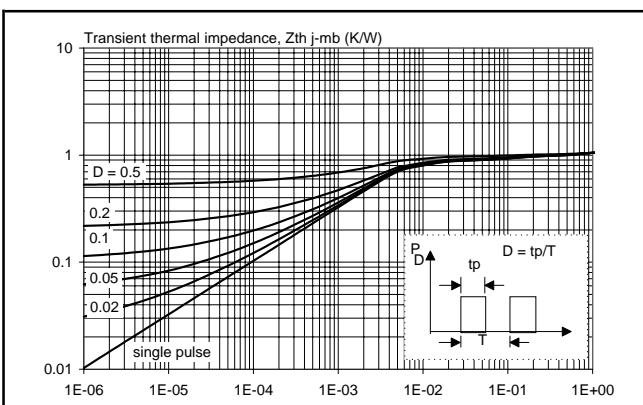


Fig. 4. Transient thermal impedance.  
 $Z_{th,j-mb} = f(t_p); \text{parameter } D = t_p/T$

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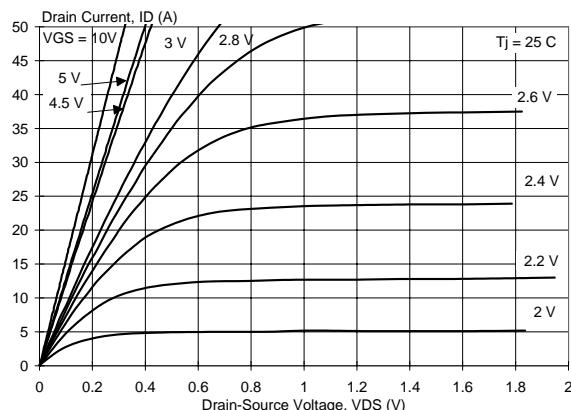


Fig.5. Typical output characteristics,  $T_j = 25^\circ\text{C}$ .  
 $I_D = f(V_{DS})$

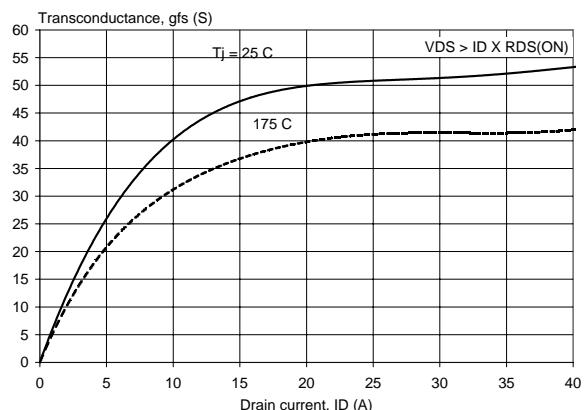


Fig.8. Typical transconductance,  $T_j = 25^\circ\text{C}$ .  
 $g_{fs} = f(I_D)$

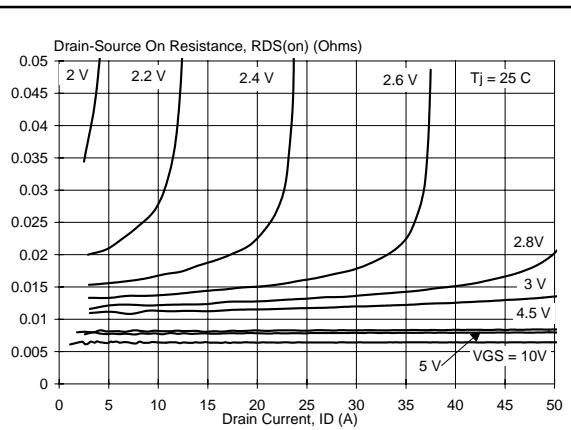


Fig.6. Typical on-state resistance,  $T_j = 25^\circ\text{C}$ .  
 $R_{DS(\text{ON})} = f(I_D)$

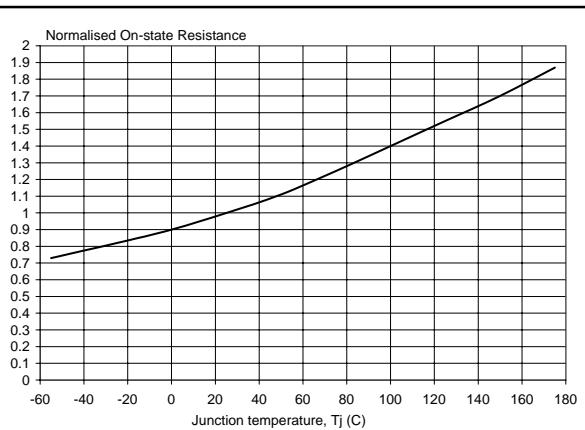


Fig.9. Normalised drain-source on-state resistance.  
 $a = R_{DS(\text{ON})}/R_{DS(\text{ON})25^\circ\text{C}} = f(T_j)$

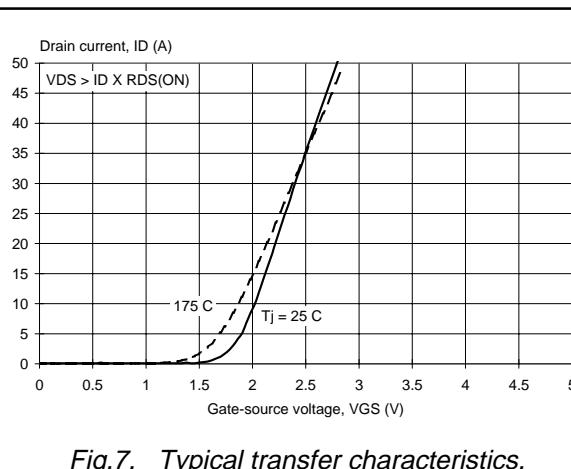


Fig.7. Typical transfer characteristics.  
 $I_D = f(V_{GS})$

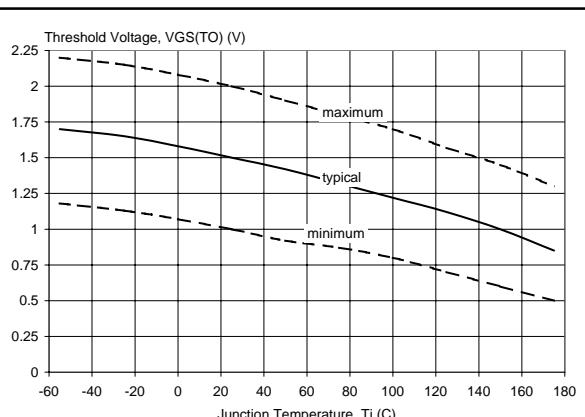
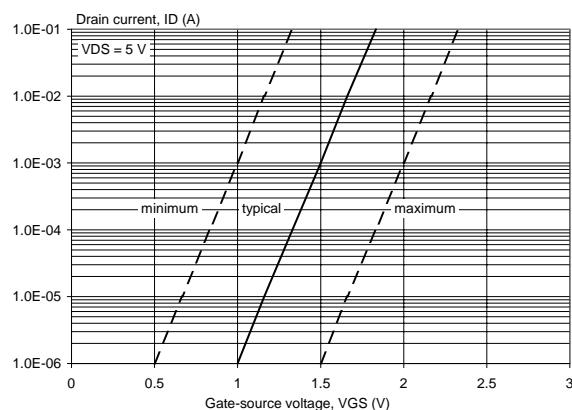


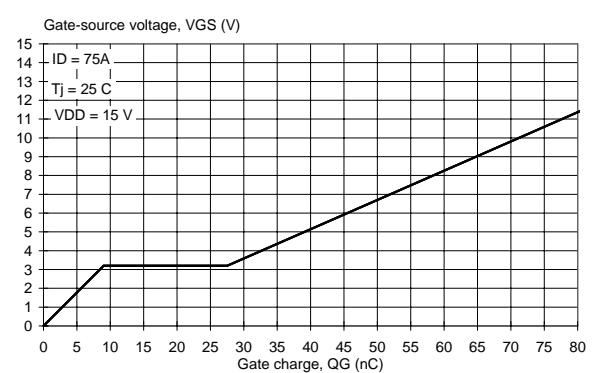
Fig.10. Gate threshold voltage.  
 $V_{GS(\text{TO})} = f(T_j)$ ; conditions:  $I_D = 1\text{ mA}$ ;  $V_{DS} = V_{GS}$

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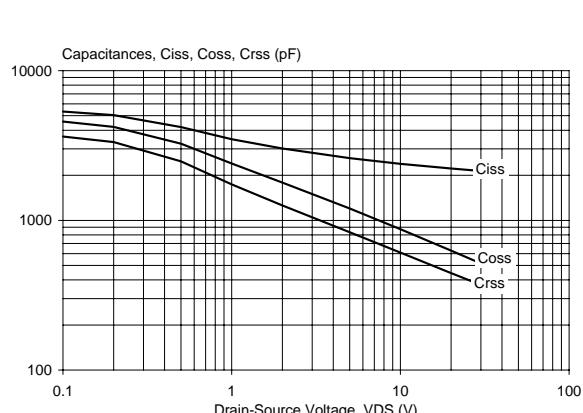
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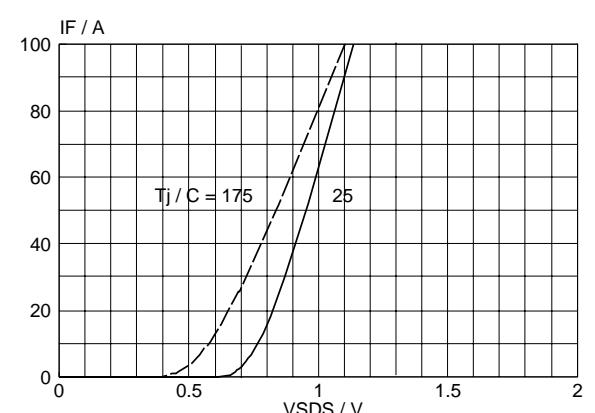
*Fig.11. Sub-threshold drain current.  
 $I_D = f(V_{GS})$ ; conditions:  $T_j = 25^\circ\text{C}$ ;  $V_{DS} = V_{GS}$*



*Fig.13. Typical turn-on gate-charge characteristics.  
 $V_{GS} = f(Q_G)$*



*Fig.12. Typical capacitances,  $C_{iss}$ ,  $C_{oss}$ ,  $C_{rss}$ .  
 $C = f(V_{DS})$ ; conditions:  $V_{GS} = 0\text{V}$ ;  $f = 1\text{MHz}$*



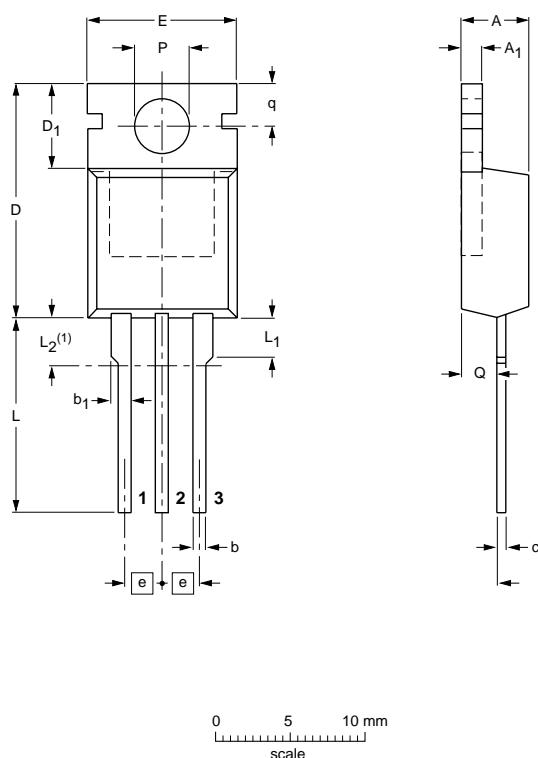
*Fig.14. Typical reverse diode current.  
 $I_F = f(V_{SDS})$ ; conditions:  $V_{GS} = 0\text{V}$ ; parameter  $T_j$*

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## MECHANICAL DATA

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220 SOT78



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub>	b	b <sub>1</sub>	c	D	D <sub>1</sub>	E	e	L	L <sub>1</sub>	L <sub>2</sub> <sup>(1)</sup> max.	P	q	Q
mm	4.5 4.1	1.39 1.27	0.9 0.7	1.3 1.0	0.7 0.4	15.8 15.2	6.4 5.9	10.3 9.7	2.54	15.0 13.5	3.30 2.79	3.0 3.6	3.8 3.0	2.6 2.2	

Note

1. Terminals in this zone are not tinned.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT78		TO-220				97-06-11

Fig.15. SOT78 (TO220AB); pin 2 connected to mounting base (Net mass:2g)

### Notes

- This product is supplied in anti-static packaging. The gate-source input must be protected against static discharge during transport or handling.
- Refer to mounting instructions for SOT78 (TO220AB) package.
- Epoxy meets UL94 V0 at 1/8".

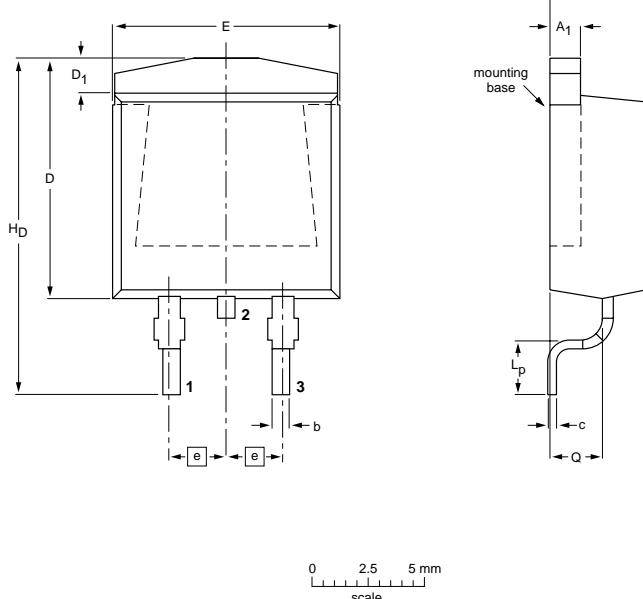
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## MECHANICAL DATA

Plastic single-ended surface mounted package (Philips version of D2-PAK); 3 leads  
(one lead cropped)

SOT404



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub>	b	c	D <sub>max.</sub>	D <sub>1</sub>	E	e	L <sub>p</sub>	H <sub>D</sub>	Q
mm	4.50 4.10	1.40 1.27	0.85 0.60	0.64 0.46	11	1.60 1.20	10.30 9.70	2.54	2.90 2.10	15.40 14.80	2.60 2.20

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT404						-98-12-14- 99-06-25

Fig.16. SOT404 surface mounting package. Centre pin connected to mounting base.

### Notes

1. This product is supplied in anti-static packaging. The gate-source input must be protected against static discharge during transport or handling.
2. Refer to SMD Footprint Design and Soldering Guidelines, Data Handbook SC18.
3. Epoxy meets UL94 V0 at 1/8".

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## MOUNTING INSTRUCTIONS

*Dimensions in mm*

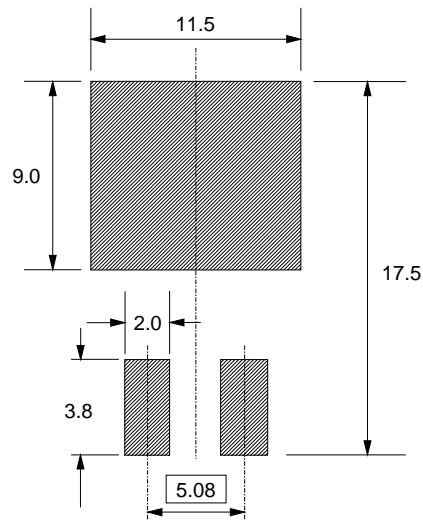


Fig.17. SOT404 : soldering pattern for surface mounting.

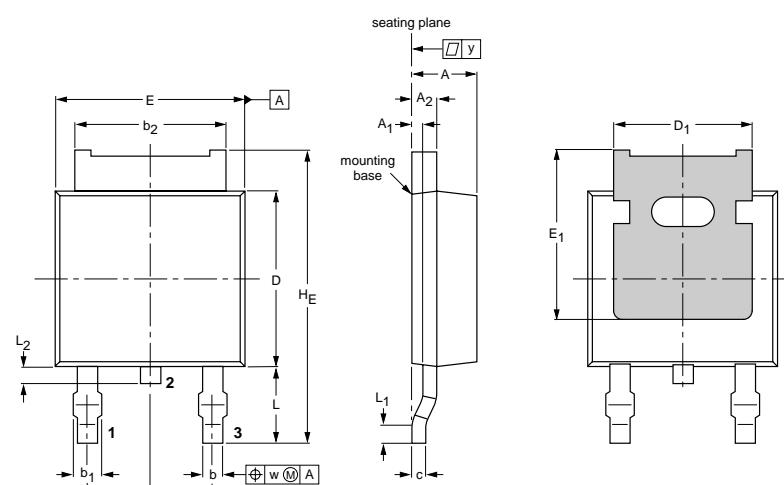
## N-channel TrenchMOS™ transistor Logic level FET

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PHD87N03LT

### MECHANICAL DATA

Plastic single-ended surface mounted package (Philips version of D-PAK); 3 leads  
(one lead cropped)

SOT428



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub> <sup>(1)</sup>	A <sub>2</sub>	b	b <sub>1</sub> max.	b <sub>2</sub>	c	D max.	D <sub>1</sub> max.	E max.	E <sub>1</sub> min.	e	e <sub>1</sub>	H <sub>E</sub> max.	L	L <sub>1</sub> min.	L <sub>2</sub>	w	y max.
mm	2.38	0.65	0.89	0.89	1.1	5.36	0.4	6.22	4.81	6.73	4.0	2.285	4.57	10.4	2.95	0.5	0.7	0.2	0.2
	2.22	0.45	0.71	0.71	0.9	5.26	0.2	5.98	4.45	6.47				9.6	2.55	0.5	0.5		

Note

1. Measured from heatsink back to lead.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT428						98-04-07

Fig.18. SOT428 surface mounting package. Centre pin connected to mounting base.

#### Notes

- This product is supplied in anti-static packaging. The gate-source input must be protected against static discharge during transport or handling.
- Refer to SMD Footprint Design and Soldering Guidelines, Data Handbook SC18.
- Epoxy meets UL94 V0 at 1/8".

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## MOUNTING INSTRUCTIONS

*Dimensions in mm*

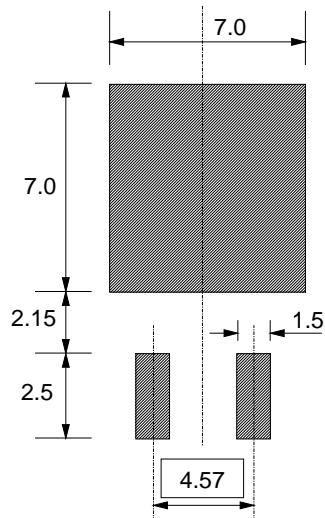


Fig.19. SOT428 : soldering pattern for surface mounting.

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## DEFINITIONS

<b>Data sheet status</b>	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
<b>Limiting values</b>	
Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
<b>Application information</b>	
Where application information is given, it is advisory and does not form part of the specification.	
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## LIFE SUPPORT APPLICATIONS

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